

■ FEATURES 特点

Compact Size 体积小

Miniaturized SMD packaged in low profile and lightweight.

Low Loss 低插入损耗

Low insertion loss, high attenuation.

High Soldering Heat Resistance 耐高温表面焊接

High quality termination allows both flow and re-flow soldering methods to be applied.

High Performance 特性优良

Eliminate noise over a wide frequency range. Idea for high frequency and space limited designs.

Internal Shielding incorporated 良好的内部屏蔽

Available in tape and reel packaging for automatic mounting 卷轴包装适用于表面贴片技术

■ Product Identification 产品型号

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 ① ② ③ ④ ⑤

- ① Product Code
- ② Dimension Code
- ③ Series Type (### represents center frequency and xx represents material type)
- ④ Design Code
- ⑤ Pattern Code